

LM4431 Micropower Shunt Voltage Reference

Check for Samples: [LM4431](#)

FEATURES

- **Small Package: SOT-23**
- **No Output Capacitor Required**
- **Tolerates Capacitive Loads**
- **Fixed Reverse Breakdown Voltage of 2.50V**

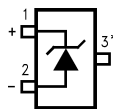
APPLICATIONS

- **Portable, Battery-Powered Equipment**
- **Data Acquisition Systems**
- **Instrumentation**
- **Process Control**
- **Energy Management**
- **Product Testing**
- **Power Supplies**

KEY SPECIFICATIONS

- **Output Voltage Tolerance: 25°C: ±2.0% (Max)**
- **Low Output Noise (10 Hz to 10 kHz): 35 μV_{rms} (Typ)**
- **Wide Operating Current Range: 100 μA to 15 mA**
- **Commercial Temperature Range: 0 to +70 °C**
- **Low Temperature Coefficient: 30 ppm/°C (Typ)**

Connection Diagram

Top View


* This pin must be left floating or connected to pin 2.

Figure 1. SOT-23 Package
See Package Number DBZ0003A



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

Absolute Maximum Ratings⁽¹⁾⁽²⁾

Reverse Current		20 mA	
Forward Current		10 mA	
Power Dissipation ($T_A = 25^\circ\text{C}$) ⁽³⁾		DBZ0003A Package 306 mW	
Storage Temperature		-65°C to +150°C	
Lead Temperature	DBZ0003A Package	Vapor phase (60 seconds)	+215°C
		Infrared (15 seconds)	+220°C
ESD Susceptibility	Human Body Model ⁽⁴⁾		2 kV
	Machine Model ⁽⁴⁾		200V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The specified specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $PD_{max} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4431, $T_{Jmax} = 125^\circ\text{C}$, and the typical thermal resistance (θ_{JA}), when board mounted, is $326^\circ\text{C}/\text{W}$ for the SOT-23 package.
- (4) The human body model is a 100 pF capacitor discharged through a 1.5 k Ω resistor into each pin. The machine model is a 200 pF capacitor discharged directly into each pin.

Operating Ratings⁽¹⁾⁽²⁾

Temperature Range ($T_{min} \leq T_A \leq T_{max}$)		$0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$
Reverse Current	LM4431-2.5	100 μA to 15 mA

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The specified specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $PD_{max} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4431, $T_{Jmax} = 125^\circ\text{C}$, and the typical thermal resistance (θ_{JA}), when board mounted, is $326^\circ\text{C}/\text{W}$ for the SOT-23 package.

LM4431-2.5 Electrical Characteristics

Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX} ; all other limits $T_A = T_J = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	Typical ⁽¹⁾	LM4431M3 Limits ⁽²⁾	Units (Limit)
V_R	Reverse Breakdown Voltage	$I_R = 100\ \mu\text{A}$	2.500		V
	Reverse Breakdown Voltage Tolerance	$I_R = 100\ \mu\text{A}$		± 50	mV (max)
I_{RMIN}	Minimum Operating Current		45	100	μA μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown Voltage Temperature Coefficient	$I_R = 10\ \text{mA}$	± 30		ppm/ $^\circ\text{C}$
		$I_R = 1\ \text{mA}$	± 30		ppm/ $^\circ\text{C}$
		$I_R = 100\ \mu\text{A}$	± 30		ppm/ $^\circ\text{C}$
$\Delta V_R/\Delta I_R$	Reverse Breakdown Voltage Change with Operating Current Change	$I_{RMIN} \leq I_R \leq 1\ \text{mA}$	0.4	1.0 1.2	mV mV (max) mV (max)
		$1\ \text{mA} \leq I_R \leq 15\ \text{mA}$	2.5	8.0 25	mV mV (max) mV (max)
Z_R	Reverse Dynamic Impedance	$I_R = 1\ \text{mA}$, $f = 120\ \text{Hz}$, $I_{AC} = 0.1\ I_R$	1.0		Ω
e_N	Wideband Noise	$I_R = 100\ \mu\text{A}$, $10\ \text{Hz} \leq f \leq 10\ \text{kHz}$	35		μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	$t = 1000\ \text{hrs}$ $T = 25^\circ\text{C} \pm 0.1^\circ\text{C}$ $I_R = 100\ \mu\text{A}$	120		ppm

(1) Typicals are at $T_J = 25^\circ\text{C}$ and represent most likely parametric norm.

(2) Limits are 100% production tested at 25°C . Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate AOQL.

Typical Performance Characteristics

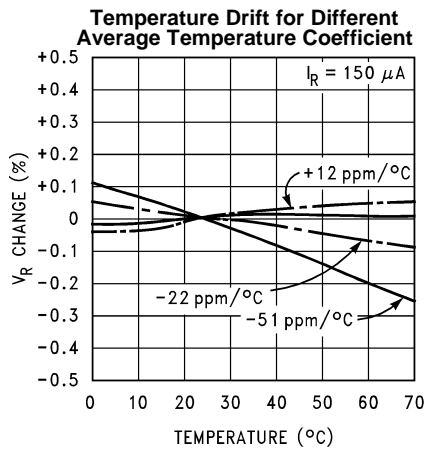


Figure 2.

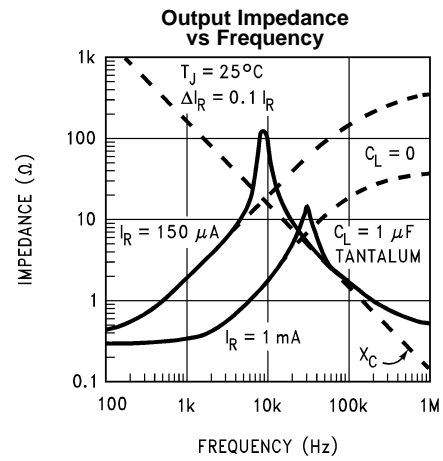


Figure 3.

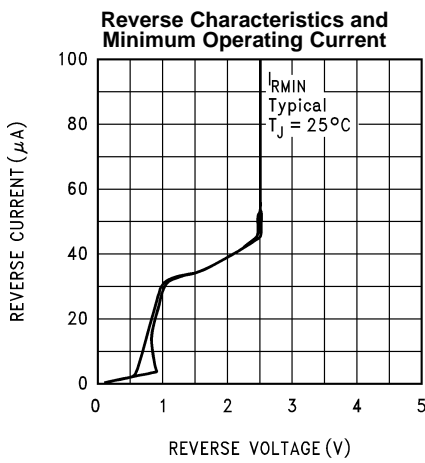


Figure 4.

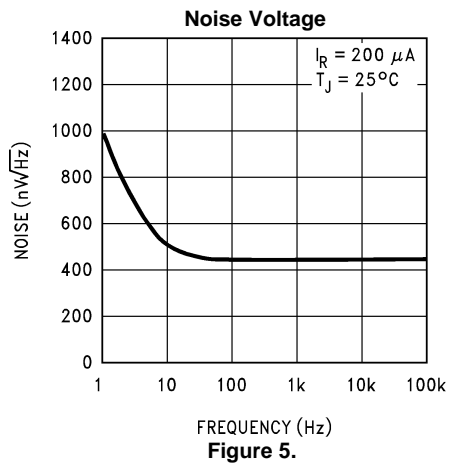


Figure 5.

Start-Up Characteristics

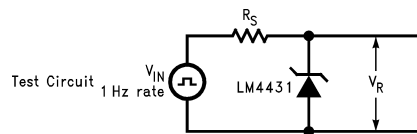


Figure 6. Test Circuit

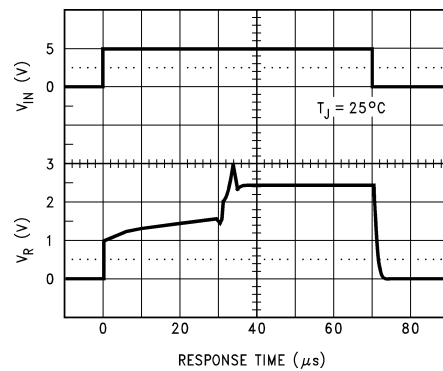
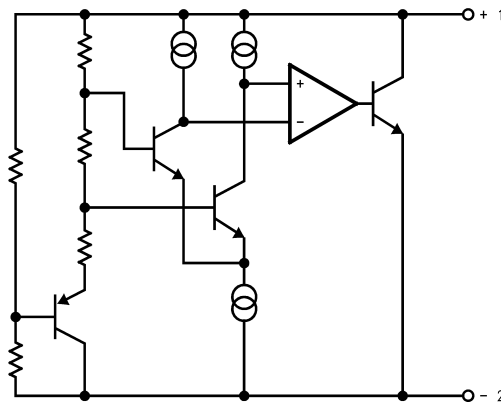


Figure 7. LM4431-2.5, R_S = 30k

Functional Block Diagram



APPLICATIONS INFORMATION

The LM4431 is a micro-power curvature-corrected 2.5V bandgap shunt voltage reference. For space critical applications, the LM4431 is available in the sub-miniature SOT-23 surface-mount package. The LM4431 has been designed for stable operation without the need of an external capacitor connected between the “+” pin and the “-” pin. If, however, a bypass capacitor is used, the LM4431 remains stable. The operating current range is 100 μ A to 15 mA.

The LM4431's SOT-23 package has a parasitic Schottky diode between pin 2 (-) and pin 3 (Die attach interface contact). Therefore, pin 3 of the SOT-23 package must be left floating or connected to pin 2.

In a conventional shunt regulator application (Figure 8), an external series resistor (R_S) is connected between the supply voltage and the LM4431. R_S determines the current that flows through the load (I_L) and the LM4431 (I_Q). Since load current and supply voltage may vary, R_S should be small enough to supply at least the minimum acceptable I_Q to the LM4431 even when the supply voltage is at its minimum and the load current is at its maximum value. When the supply voltage is at its maximum and I_L is at its minimum, R_S should be large enough so that the current flowing through the LM4431 is less than 15 mA.

R_S is determined by the supply voltage, (V_S), the load and operating current, (I_L and I_Q), and the LM4431's reverse breakdown voltage, V_R .

$$R_S = \frac{V_S - V_R}{I_L + I_Q} \quad (1)$$

Typical Applications

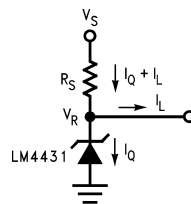


Figure 8. Shunt Regulator

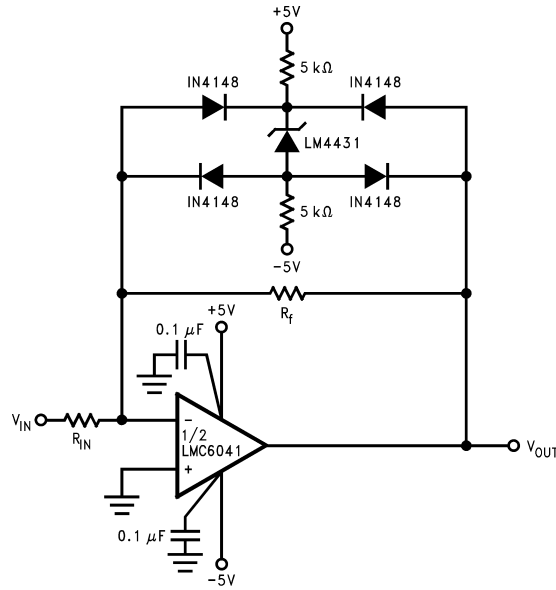


Figure 9. Bounded amplifier reduces saturation-induced delays and can prevent succeeding stage damage.
 Nominal clamping voltage is $\pm 3.9V$ (LM4431's reverse breakdown voltage + 2 diode V_F).

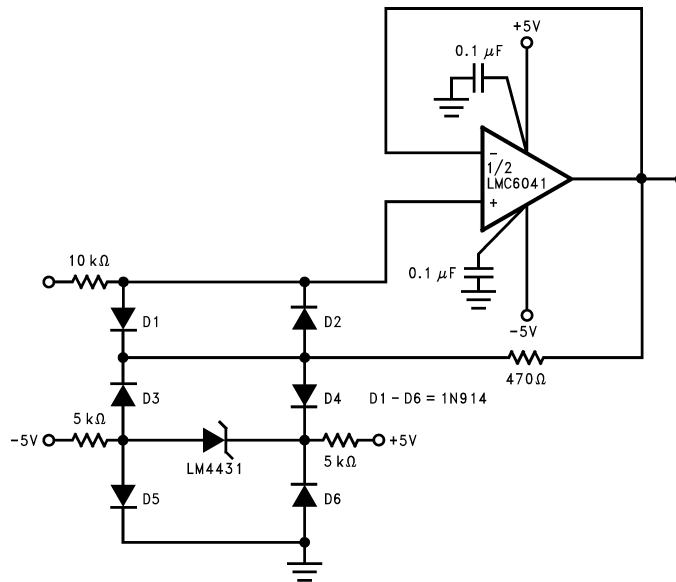
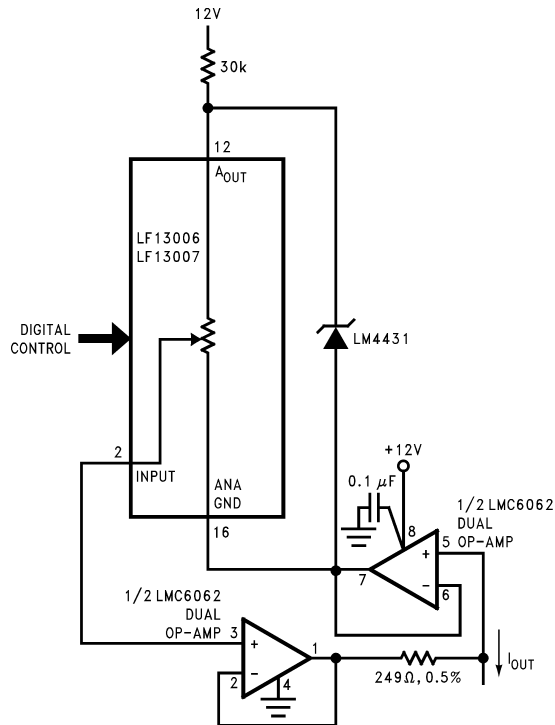
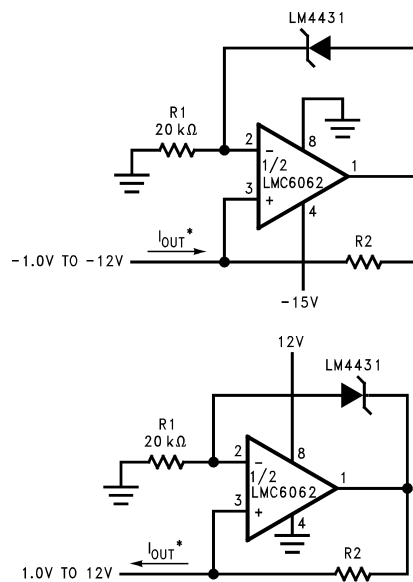


Figure 10. Protecting Op amp input.
 The bounding voltage is $\pm 4V$ with the LM4431 (LM4431's reverse breakdown voltage + 3 diode V_F).



$$I_{OUT} = \frac{2.5V}{249\Omega} \left[\frac{1}{\text{gain set \#}} \right]$$

Figure 11. Programmable Current Source



$$I_{OUT}^* = \frac{2.5V}{R2}$$

Figure 12. Precision 1 μA to 1 mA Current Sources

REVISION HISTORY

Changes from Revision B (April 2013) to Revision C	Page
• Changed layout of National Data Sheet to TI format	7

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM4431M3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	0 to 70	S2E	
LM4431M3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	S2E	Samples
LM4431M3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	S2E	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4431M3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4431M3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4431M3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

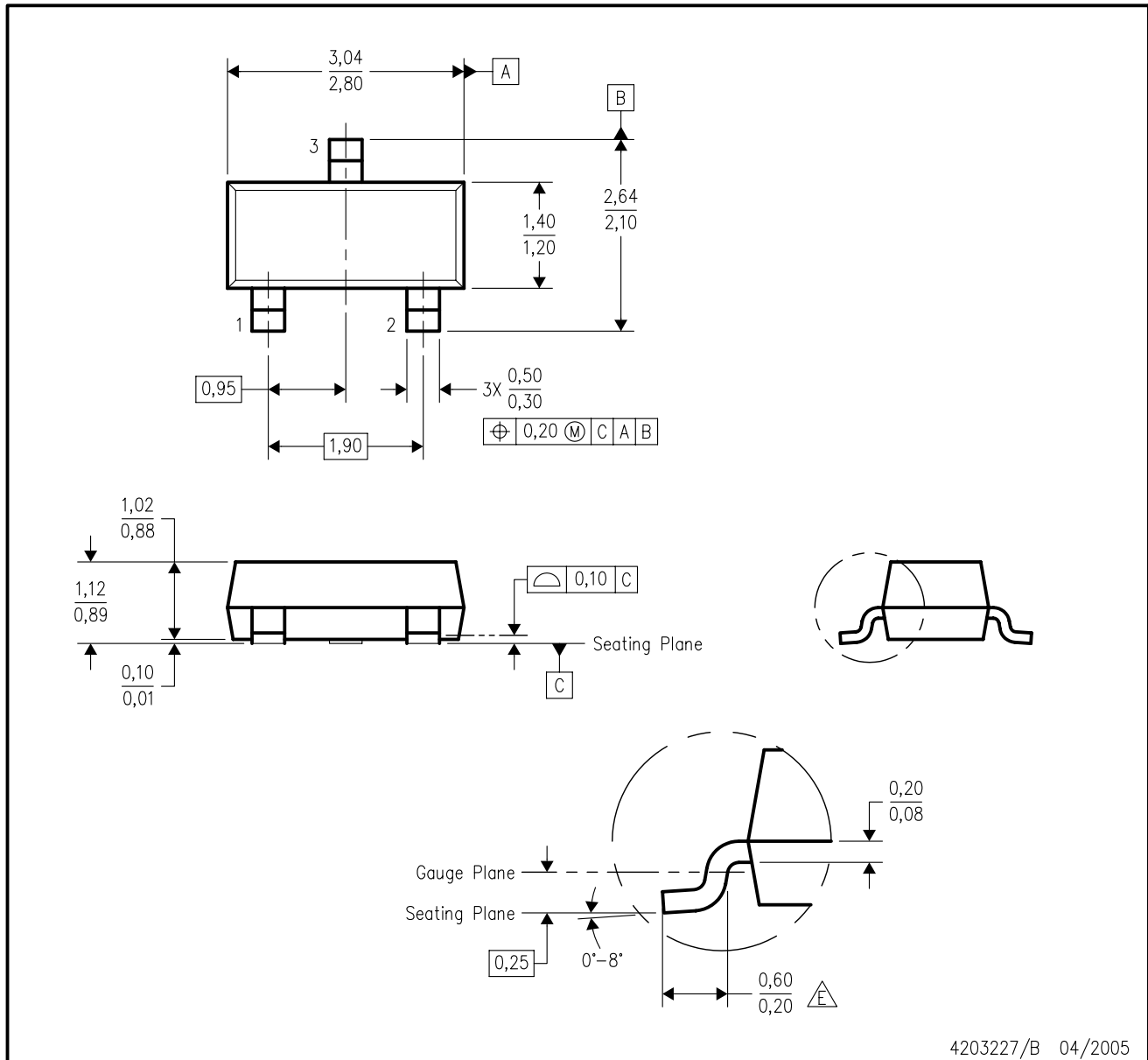
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4431M3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4431M3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4431M3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Lead dimensions are inclusive of plating.
 - D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com